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SCOPE PROBE CONNECTIONS

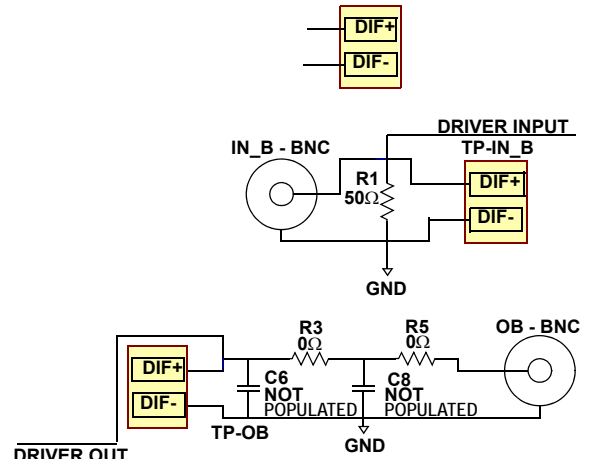


FIGURE 1. DUAL .1" SPACED PINS ARE PLACED ON THE EVALUATIONS BOARDS FOR LEADLESS ACTIVE PROBE CONNECTIONS

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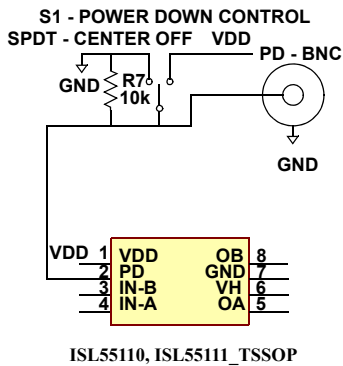


FIGURE 2. TSSOP AND QFN EVALUATION BOARDS HAVE THE SAME POWER DOWN CIRCUITRY

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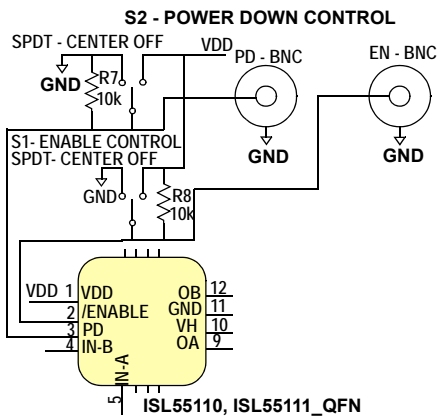


FIGURE 3. QFN PACKAGES HAVE BOTH POWER DOWN AND OUTPUT ENABLE DIGITAL INPUTS

Initial Power Up

Please refer to the device specification for power up sequencing and current requirements. Also note that the frequency of operation of each driver will determine the current needed. There are graphs in the specification regarding current characteristics.

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Driver Loads

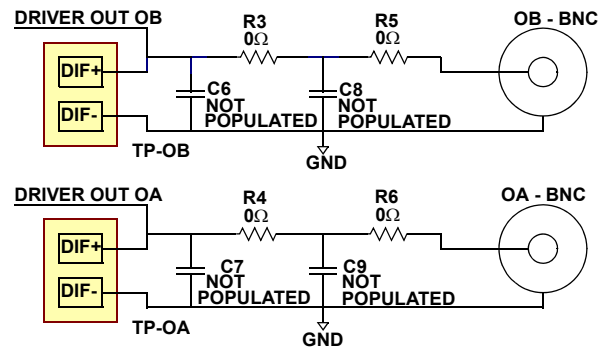


FIGURE 4. CUSTOM LOAD COMPONENTS

Component locations C6 to C7 and R3 to R6 are surface mount locations provided so the user can experiment with various load configurations.

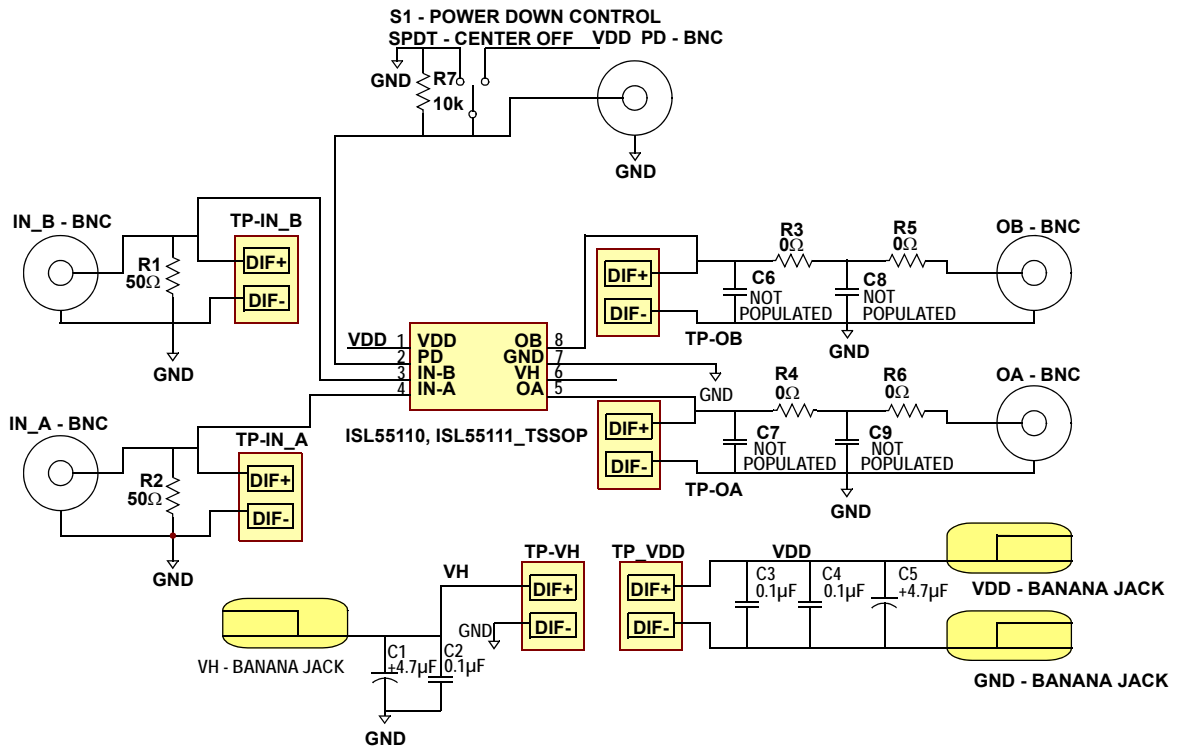


FIGURE 5. TSSOP EVALUATION BOARD SCHEMATIC

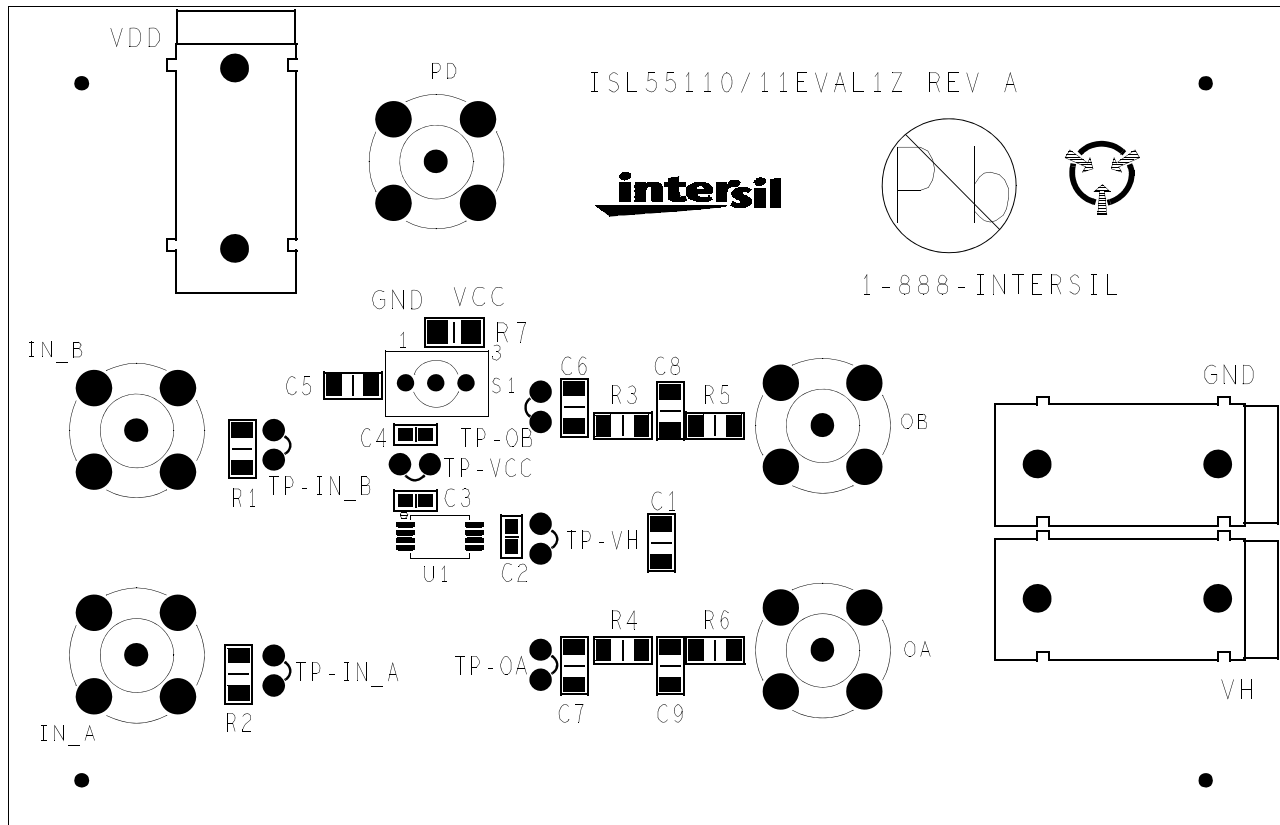


FIGURE 6. TSSOP LAYOUT

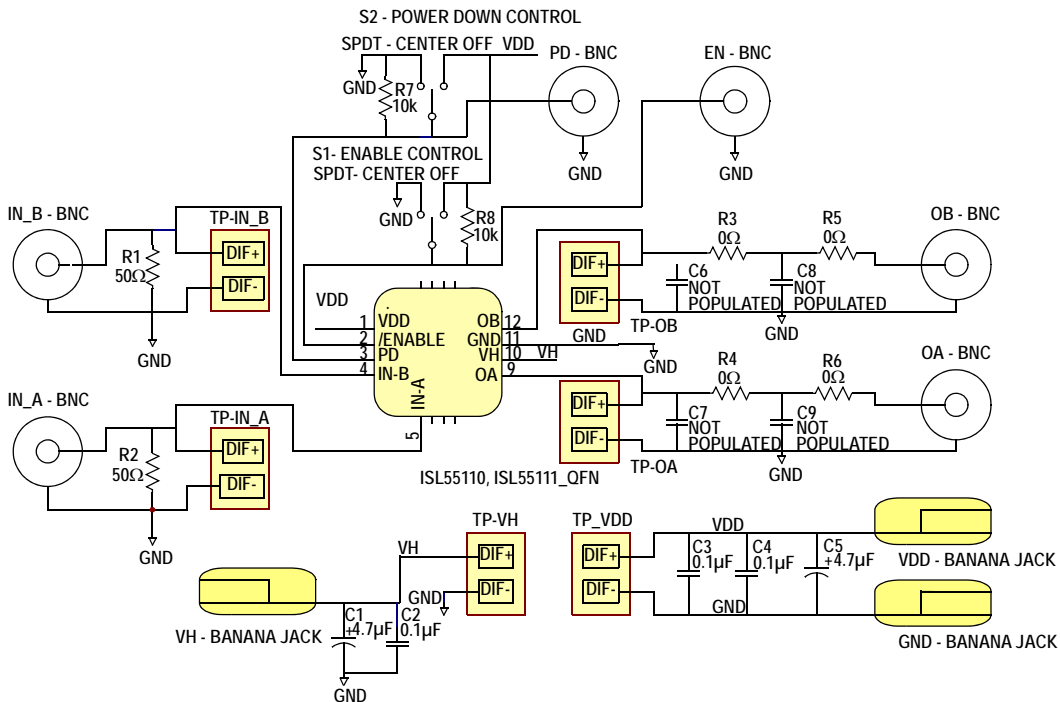


FIGURE 7. QFN EVALUATION BOARD SCHEMATIC

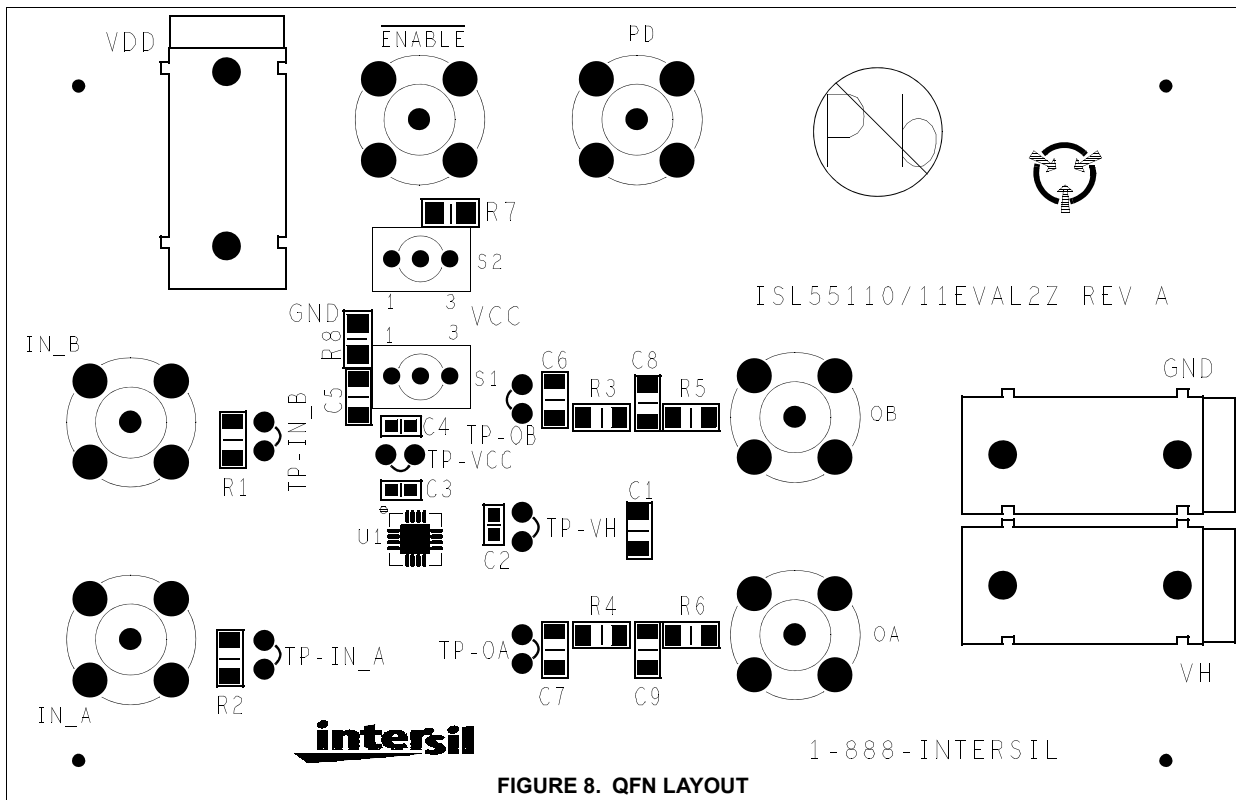


FIGURE 8. QFN LAYOUT

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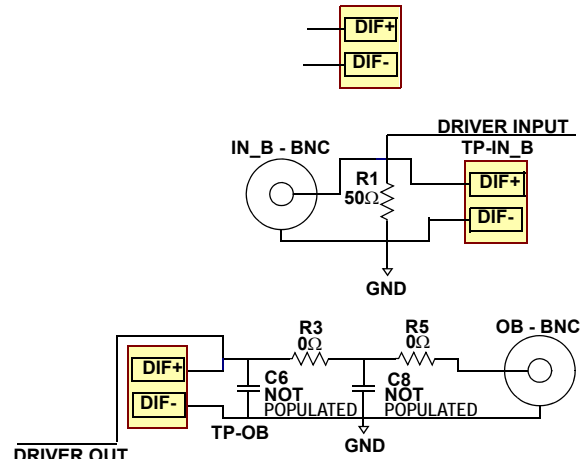


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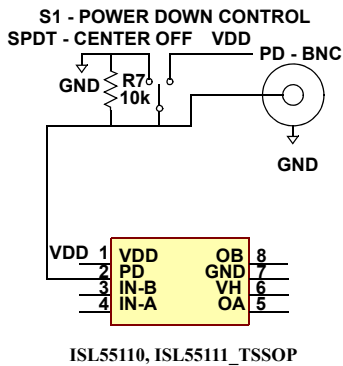


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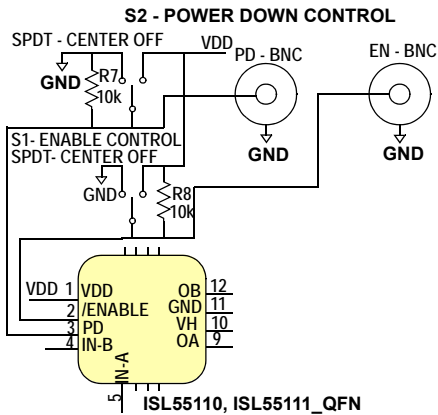


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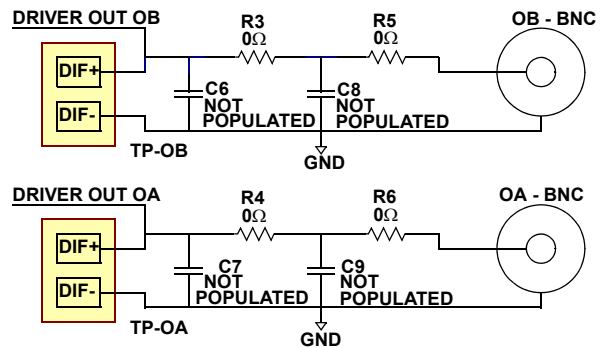


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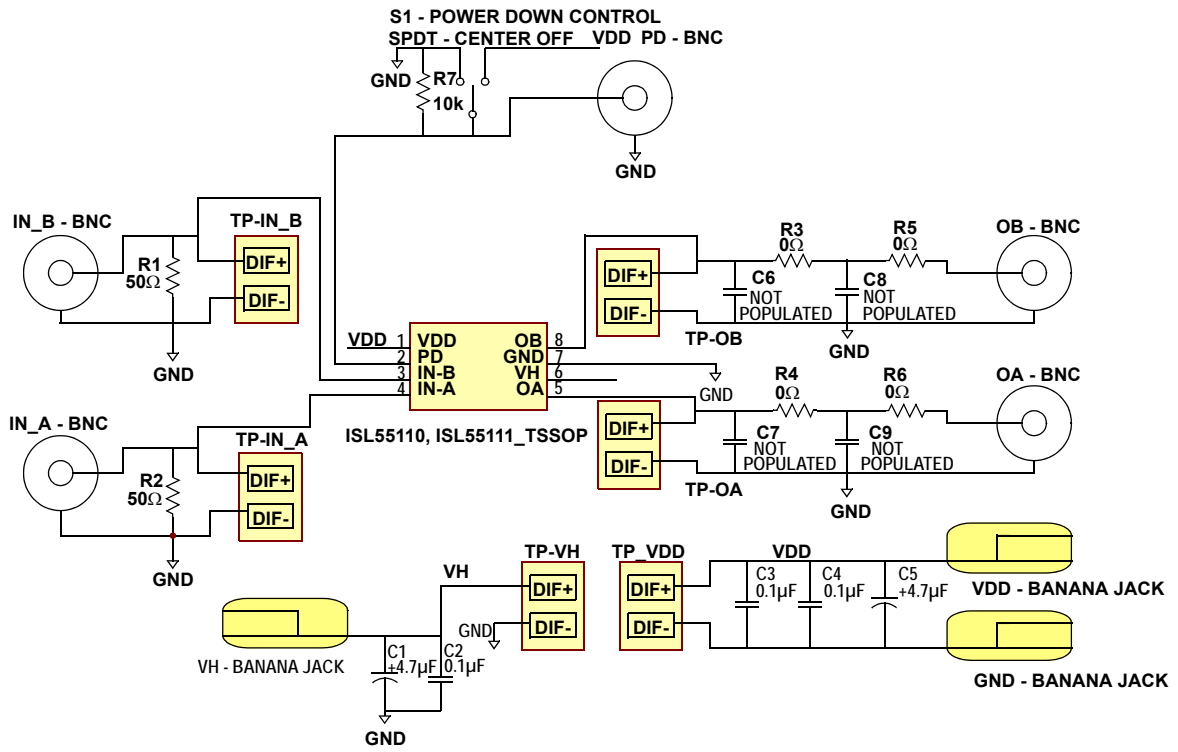


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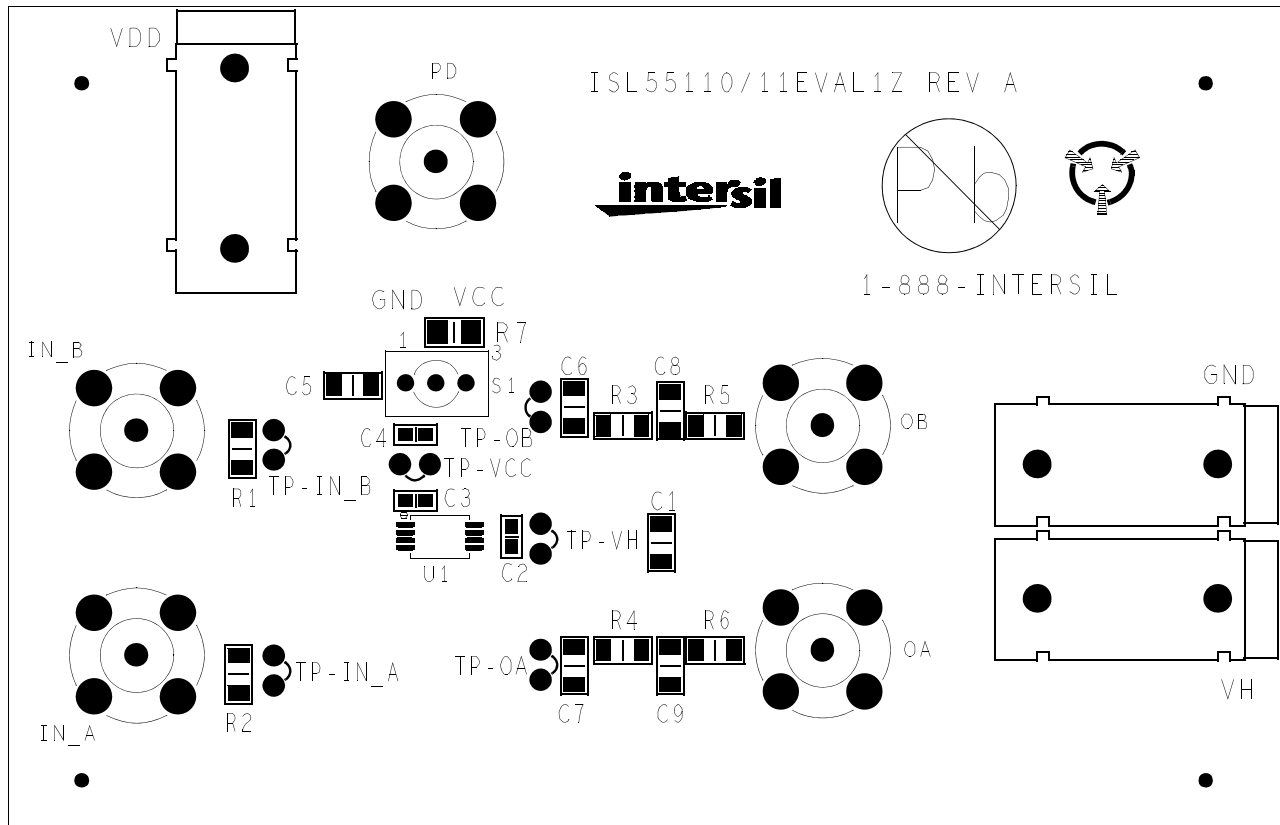


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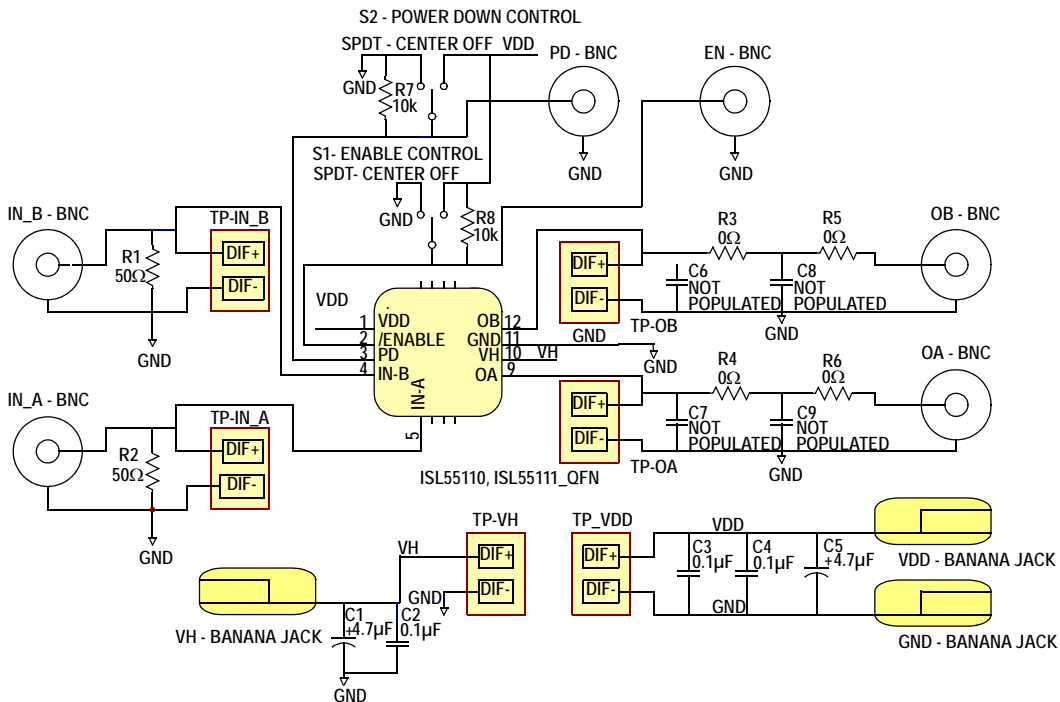


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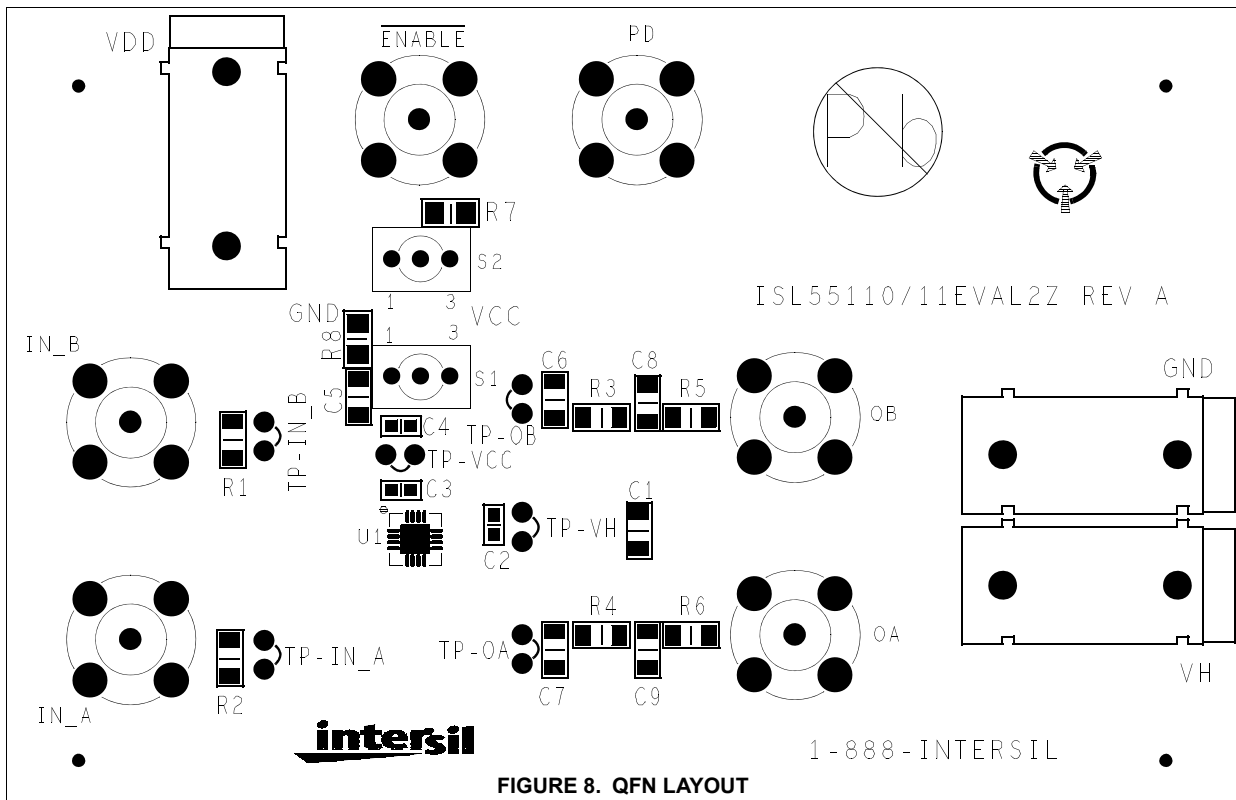


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